Pb Free Plating Product

BA30MP/BA30MN

30 Ampere Avalanche Type Block Rectifier Diodes for Mitsubishi Alternator

Feature:

- Low leakage
- Low forward voltage drop
- High current capability
- High forward surge current capability

Application:

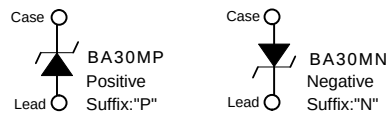
- Block Diode/Alternator Diode with AEC-Q101 Grade Quality
- Stack Silicon Diffused Diode alternative
- Special for Automotive AC Alternator rectifier application

Mechanical Data:

- Technology: Latest Glass Passivation Pellet/Cu Clip Bonding
- Case: Vacuum soldered/Sintered temperature < 260℃
- Cathode Polarity: As marked on body
- Lead: Plated lead, solderable per MIL-STD-202E method 208C
- Mounting: BLOCK/TO-230/BA/MR/K series package type

BLOCK/TO-230/BA/MR/K series





MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

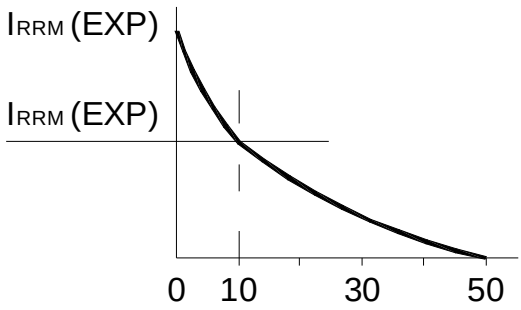
- Ratings at 25℃ ambient temperature unless otherwise specified
- Single Phase, half wave, 60Hz, resistive or inductive load
- For capacitive load derate current by 20%

		BA30MP/BA30MN			
Electrical Characteristics @ 25℃	SYMBOLS	MIN	NOMINAL	MAX	UNITS
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage Transient Peak Reverse Voltage	V_{RRM} V_{RRM} V_{DC} V_{RSM}		28 28 28		Volts
Average Rectified Forward Current (Tc=125℃)	Io		30		Amps
Repetitive Peak Reverse Surge Current Tc=10msec Dury Cycle＜1%	I_{RSM}		30		Amps
Breakdown Voltage (Vbr@ir=100mA, Tc=25℃) Ir=90Amps, Tc=150℃, PW=80usec Zener Voltage	Vbr1 Vz Vbr2	37	39	41 54	Volts Volts
Forward Voltage Drop @If=100Amps＜300usec	V_F		1.05	1.10	Volts
Peak Forward Surge Current	I_{FSM}		400		Amps
Reverse Leakage (V_R=17Vdc) T_A=25℃	I_R		1.0	2.0	uAmps
Operating and Storage Junction Temperature Range	T_J ,T_{STG}		-65 to +175		℃

Notes: 1. Enough heatsink must be considered in application.

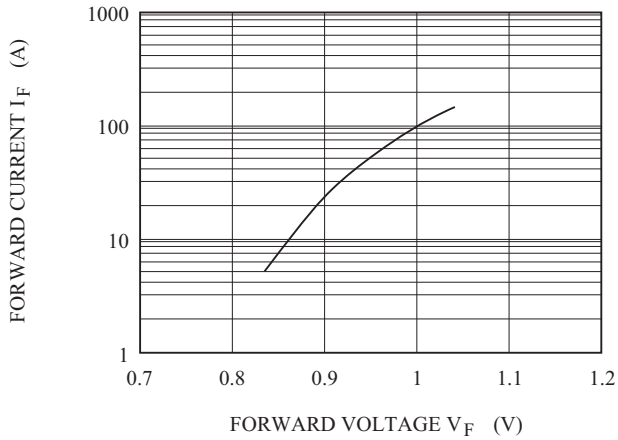
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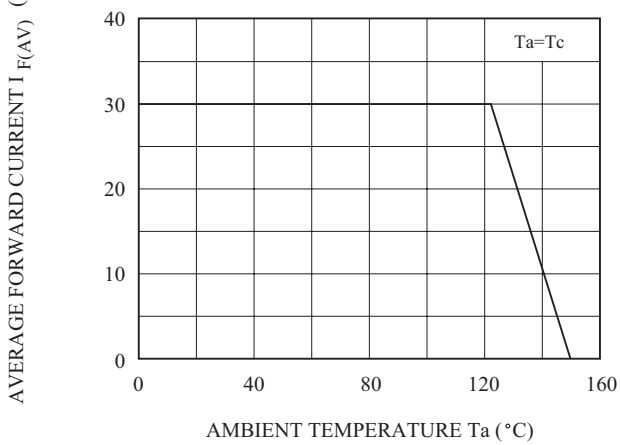


Surge current characteristics

I_F - V_F



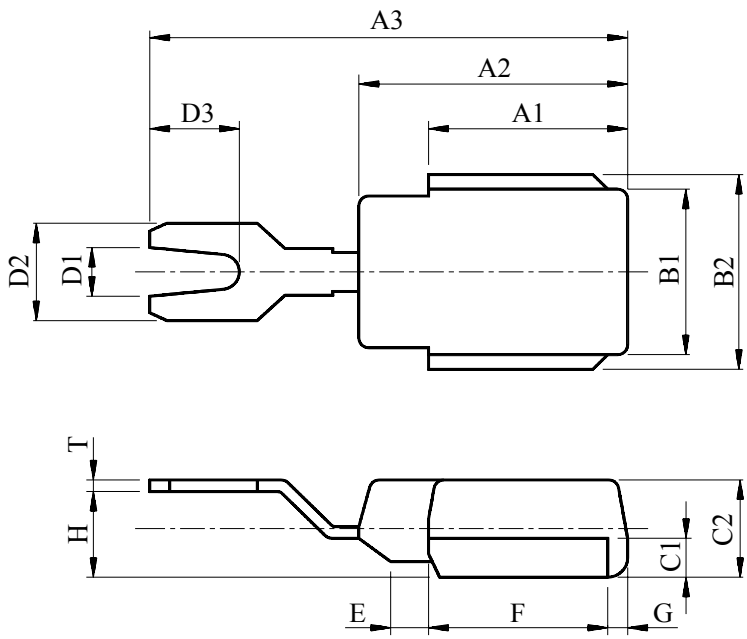
$I_{F(AV)}$ - Ta



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BLOCK/TO-230/BA/MR/K Series Package Outline



DIM	MILLIMETERS	DIM	MILLIMETERS
A1	10.0±0.3	D2	5.0±0.3
A2	13.5±0.3	D3	4.5±0.3
A3	24.0±0.5	E	1.9±0.3
B1	8.5±0.3	F	9.0±0.3
B2	10.0±0.3	G	1.0±0.3
C1	2.0±0.3	H	4.4±0.5
C2	5.0±0.3	T	0.6±0.3
D1	2.5±0.3		

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